



Product Change Notification

108147 - 01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 108147 - 01
Change Title: CE6353,PCN 108147-01, Manufacturing Site, Qualification of Additional Assembly and Test Site, Reason for Revision: Additional Product Mark Information
Date of Publication: January 28, 2008

Key Characteristics of the Change:

Manufacturing Site
Product Marking

Forecasted Key Milestones:

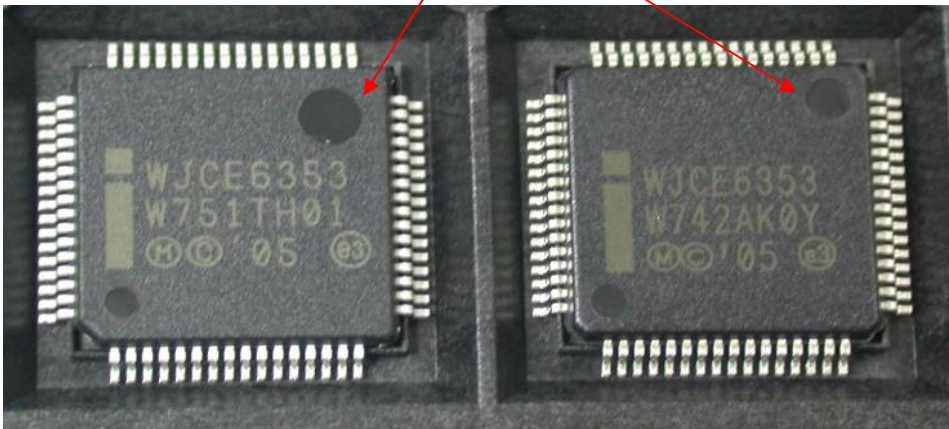
Date of Samples Availability:	Feb 15, 2008
Date Customer Must be Ready to Receive Post-Conversion Material:	Apr 18, 2008

Description of Change to the Customer:

Reason for Revision: Additional Mark Information

There is a slight difference between the parts coming from each site in the mold eject pin size, please see below. Again there is no form, fit, function, or reliability difference between the products coming from either site. The difference is cosmetic only. Customers should be prepared to accept product with either mark.

Mold eject pin mark size is different



In order to ensure a continuous supply of Intel's CE6353, Intel will be qualifying an additional assembly and test site. The new site will be located in Shanghai, China. Traceability will be maintained through the site identification code included within the finished process order (FPO) mark.

Customer Impact of Change and Recommended Action:

Intel does not anticipate any impact to the customer with this change. Customers should be ready to receive product from this as well as all other qualified existing assembly/test sites for these products.

Products Affected / Intel Ordering Codes:

Pre Conversion Product Code	Pre Conversion S-Spec	Pre Conversion MM#
WJCE6353 S L9G5	S L9G5	882170
WJCE6353 882206		882206

Reference Documents / Attachments:

Document: _____ **Location #:** _____

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
December 12, 2007	00	Originally Published PCN
January 28, 2008	01	Additional Mark Information